

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC8107xxxxMR-G

Typical Mass: 16 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.440	Silicon	27500	7440-21-3
		- Arsenic	<1	7440-38-2
Leadframe	5.503	Copper	343900	7440-50-8
		Tin	1400	7440-31-5
		Zinc	1300	7440-66-6
		Chromium	1500	7440-47-3
		Silver	20300	7440-22-4
		Die attach	0.049	Silver
Epoxy	600	—		
Bonding wire	0.106	Gold	6600	7440-57-5
Resin	7.437	Silica	464800	60676-86-0
		Epoxy resin	44200	—
		Phenol resin	37200	—
		Metal hydroxide	26400	—
Plating	0.340	Tin	21300	7440-31-5

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."